

P-Channel 60 V (D-S) MOSFET

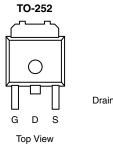
PRODUCT SUMMARY					
V _{DS} (V)	R_{DS(on)} (Ω)	I _D (A) ^d	Q _g (Typ)		
- 60	0.053 at V _{GS} = - 10 V	- 25	26		
- 00	0.062 at V_{GS} = - 4.5 V	- 20	20		

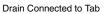
FEATURES

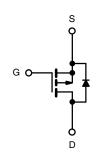
- Halogen-free According to IEC 61249-2-21
 Definition
- TrenchFET[®] Power MOSFET
- 100 % UIS Tested
- Compliant to RoHS Directive 2002/95/EC

APPLICATIONS

- High Side Switch for Full Bridge Converter
- DC/DC Converter for LCD Display







P-Channel MOSFET

ABSOLUTE MAXIMUM RATINGS ($T_A = 25$ °C, unless otherwise note)					
Parameter	Symbol	Limit	Unit		
Drain-Source Voltage	V _{DS}	- 60	v		
Gate-Source Voltage	V _{GS}	± 20	v		
Continuous Drain Current (T_{I} = 150 °C)	T _C = 25 °C	I_	- 25		
$Commutous Drain Current (1) = 150^{\circ} C)$	T _C = 125 °C		- 20	•	
Pulsed Drain Current	I _{DM}	- 100	A		
Avalanche Current, Single Pulse	L = 0.1 mH	I _{AS}	- 22		
Repetitive Avalanche Energy, Single Pulse ^a	L = 0.1 mH	E _{AS}	24.2	mJ	
Dever Dissischier	T _C = 25 °C	P _D	38.5 ^c	- w	
Power Dissipation	T _A = 25 °C		2.3 ^{b, c}		
Operating Junction and Storage Temperature Range	T _J , T _{stg}	- 55 to 150	°C		

THERMAL RESISTANCE RATINGS						
Parameter		Symbol	Typical	Maximum	Unit	
Maximum hundling to Anthing b	t ≤ 10 s	R _{thJA}	17	21	°C/W	
Maximum Junction-to-Ambient ^b	Steady State		45	55		
Maximum Junction-to-Case	•	R _{thJC}	2.7	3.25		
Notes:						

a. Duty cycle \leq 1 %.

b. When mounted on 1" square PCB (FR-4 material).

c. See SOA curve for voltage derating.

d. Based up on $T_C = 25$ °C.

Parameter Static Static Drain-Source Breakdown Voltage Gate Threshold Voltage Gate-Body Leakage Gate-Body Leakage Zero Gate Voltage Drain Current On-State Drain Current ^a Drain-Source On-State Resistance ^a Forward Transconductance ^a Input Capacitance	Symbol V _{DS} V _{GS(th)} I _{GSS}	V _{GS} = 0 V, I _D = - 250 μA V _{DS} = V _{GS} , I _D = - 250 μA V _{DS} = 0 V, V _{GS} = ± 20 V V _{DS} = - 60 V, V _{GS} = 0 V	Min . - 60 - 1	Typ.	Max.	Unit V	
Drain-Source Breakdown Voltage Gate Threshold Voltage Gate Threshold Voltage Gate-Body Leakage Zero Gate Voltage Drain Current On-State Drain Current ^a Drain-Source On-State Resistance ^a Forward Transconductance ^a Dynamic ^b	V _{GS(th)} I _{GSS}	$V_{DS} = V_{GS}, I_D = -250 \ \mu A$ $V_{DS} = 0 \ V, V_{GS} = \pm 20 \ V$				V	
Gate Threshold Voltage Gate-Body Leakage Zero Gate Voltage Drain Current On-State Drain Current ^a Drain-Source On-State Resistance ^a Forward Transconductance ^a Dynamic ^b	V _{GS(th)} I _{GSS}	$V_{DS} = V_{GS}, I_D = -250 \ \mu A$ $V_{DS} = 0 \ V, V_{GS} = \pm 20 \ V$				V	
Gate-Body Leakage	I _{GSS}	$V_{DS} = 0 V, V_{GS} = \pm 20 V$	- 1				
Zero Gate Voltage Drain Current On-State Drain Current ^a Drain-Source On-State Resistance ^a Forward Transconductance ^a Dynamic ^b			1	1	- 3	V	
On-State Drain Current ^a Drain-Source On-State Resistance ^a Forward Transconductance ^a Dynamic ^b	I _{DSS}	M = 60 M M = 0 M	l		± 100	nA	
On-State Drain Current ^a Drain-Source On-State Resistance ^a Forward Transconductance ^a Dynamic ^b	I _{DSS}	$v_{DS} = -60 v, v_{GS} = 0 v$			- 1	μΑ	
Drain-Source On-State Resistance ^a Forward Transconductance ^a Dynamic ^b		V_{DS} = - 60 V, V_{GS} = 0 V, T_{J} = 125 °C			- 50		
Drain-Source On-State Resistance ^a Forward Transconductance ^a Dynamic ^b		V_{DS} = - 60 V, V_{GS} = 0 V, T_{J} = 150 $^{\circ}$ C			- 125	1	
Forward Transconductance ^a Dynamic ^b	I _{D(on)}	$V_{DS} = -5 V, V_{GS} = -10 V$	- 30			А	
Forward Transconductance ^a Dynamic ^b		V _{GS} = - 10 V, I _D = - 10 A		0.053	0.060		
Forward Transconductance ^a Dynamic ^b	D	V_{GS} = - 10 V, I _D = - 10 A, T _J = 125 °C			0.102	Ω	
Dynamic ^b	R _{DS(on)}	V_{GS} = - 10 V, I _D = - 10 A, T _J = 150 °C			0.120		
Dynamic ^b		V _{GS} = - 4.5 V, I _D = - 5 A		0.062	0.070		
•	9 _{fs}	V _{DS} = - 15 V, I _D = - 10 A		22		S	
Input Capacitance							
	C _{iss}			1140	1710	pF	
Output Capacitance	C _{oss}	$V_{GS} = 0 V$, $V_{DS} = -25 V$, f = 1 MHz		130			
Reverse Transfer Capacitance	C _{rss}			90			
Total Gate Charge ^c	Qg			26	40		
Gate-Source Charge ^c	Q _{gs}	$V_{DS} = -30$ V, $V_{GS} = -10$ V, $I_{D} = -10$ A		4.5		nC	
Gate-Drain Charge ^c	Q _{gd}			7		1	
Gate Resistance	Rg	f = 1 MHz		7		Ω	
Turn-On Delay Time ^c	t _{d(on)}			8	15	[
Rise Time ^c	t _r	V_{DD} = - 30 V, R_L = 3 Ω		9	15	ns	
Turn-Off Delay Time ^c	t _{d(off)}	$I_D \cong$ - 19 Å, V_{GEN} = - 10 V, R_g = 2.5 Ω		65	100		
Fall Time ^c	t _f			30	45		
Drain-Source Body Diode and Characteristics $(T_c = 25 \ ^{\circ}C)^{b}$							
Continuous Current	I _S				- 30		
Pulsed Current	I _{SM}			<u> </u>	- 30	A	
Forward Voltage ^a		I					
Reverse Recovery Time	V_{SD}	I _F = - 19 A, V _{GS} = 0 V		- 1	- 1.5	V	

emi

Notes:

a. Pulse test; pulse width \leq 300 $\mu s,$ duty cycle \leq 2 %.

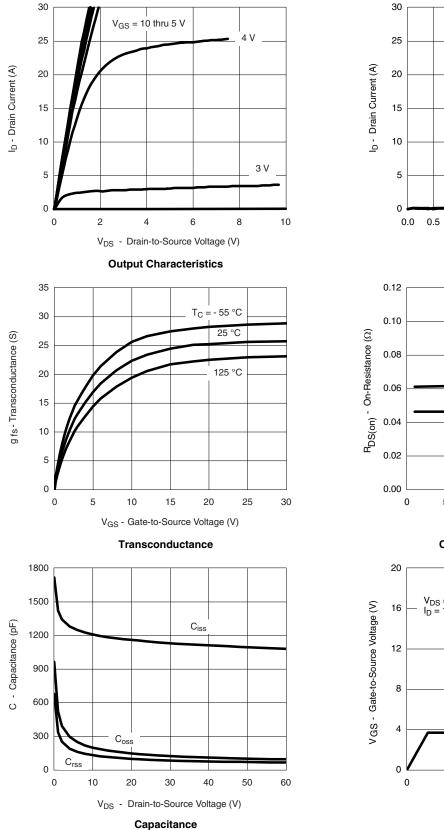
b. Guaranteed by design, not subject to production testing.

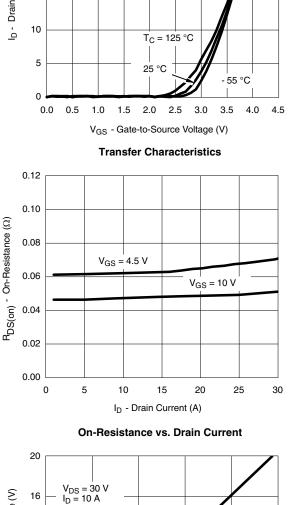
c. Independent of operating temperature.

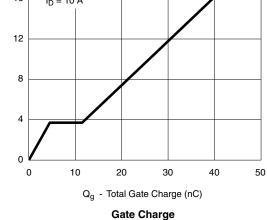
Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.



TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)

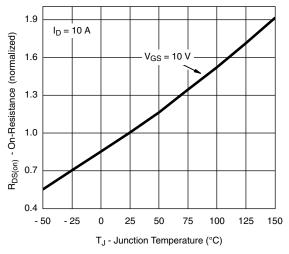






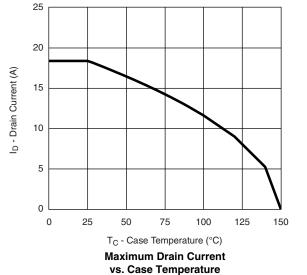


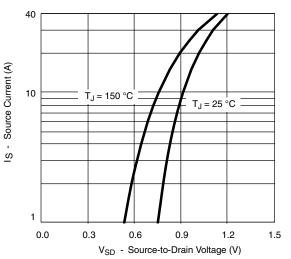
TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)



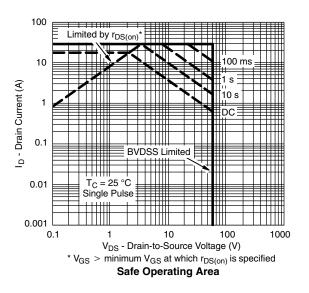
On-Resistance vs. Junction Temperature

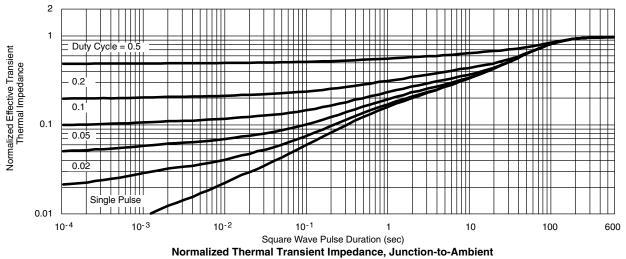






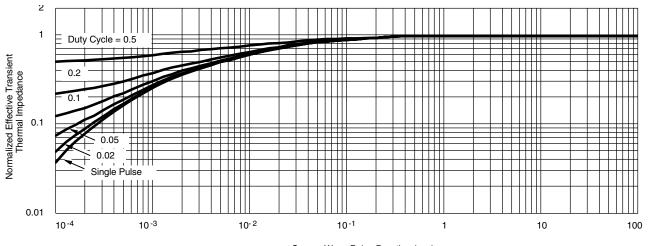
Source-Drain Diode Forward Voltage







THERMAL RATINGS

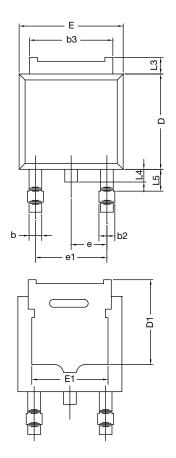


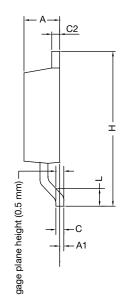
Square Wave Pulse Duration (sec)

Normalized Thermal Transient Impedance, Junction-to-Case



TO-252AA Case Outline





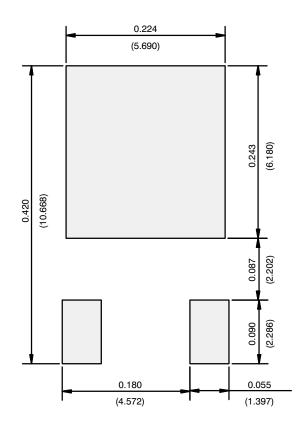
	MILLIMETERS		INC	HES		
DIM.	MIN.	MAX.	MIN.	MAX.		
А	2.18	2.38	0.086	0.094		
A1	-	0.127	-	0.005		
b	0.64	0.88	0.025	0.035		
b2	0.76	1.14	0.030	0.045		
b3	4.95	5.46	0.195	0.215		
С	0.46	0.61	0.018	0.024		
C2	0.46	0.89	0.018	0.035		
D	5.97	6.22	0.235	0.245		
D1	4.10	-	0.161	-		
E	6.35	6.73	0.250	0.265		
E1	4.32	-	0.170	-		
Н	9.40	10.41	0.370	0.410		
е	2.28	BSC	0.090	BSC		
e1	4.56	BSC	0.180	BSC		
L	1.40	1.78	0.055	0.070		
L3	0.89	1.27	0.035	0.050		
L4	-	1.02	-	0.040		
L5	1.01	1.52	0.040	0.060		
	ECN: T16-0236-Rev. P, 16-May-16 DWG: 5347					

Notes

• Dimension L3 is for reference only.



RECOMMENDED MINIMUM PADS FOR DPAK (TO-252)



Recommended Minimum Pads Dimensions in Inches/(mm)



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